



## Novel Methods for Investigating Biomolecular Interactions

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### Message from the Guest Editors

Dear Colleagues,

We are currently seeing a new wave of biological techniques to create and study biological assemblies, going to the point that new scientific sub-disciplines are emerging, as is the case of epigenetics.

In this Special Issue we will look at how technologies are being refined, for example, the way micro-probes are being in crystallography in new combinations of methods; and, for example, combining structural methods such as NMR or crystallography with docking calculations to make totally new methods, such as silicon nanotweezer measurement of DNA mechanical properties or lab-on-a-chip TEM for investigating assembly in solution to allow us to study and identify the new processes of assembly created by biologists. One clear example for which papers are particularly welcome is the use of 3D printing in the study of biomolecular and biological processes. Finally, the use of data mining to compile the information present in the literature and analyse trends and correlations previously unseen has potential.

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## Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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